Embedded USB Mass Storage Drive (e230)

MTFDCAE002SAJ, MTFDCAE002SAJ-1M1, MTFDCAE002SAJ-1M1T

MTFDCAE004SAJ, MTFDCAE004SAJ-1N1, MTFDCAE004SAJ-1N1T

MTFDCAE008SAJ, MTFDCAE008SAJ-1N1, MTFDCAE008SAJ-1N1T

MTFDCAE016SAJ, MTFDCAE016SAJ-1N1, MTFDCAE016SAJ-1N1T

Features

- Micron® NAND Flash
- Interface: Universal Serial Bus (USB) Specification, Revision 2.0
- USB support
  - USB Specification, Revisions 2.0, 1.1
  - USB Mass Storage Class Specification, Revision 1.0
- Performance
  - Sequential READ[1]: 30 MB/s
  - Sequential WRITE[1]: 22 MB/s (2GB and 4GB); 28 MB/s (8GB and16GB)
- Reliability: >1 million device hours mean time between failure (MTBF)
- Endurance: useful operating life of at least 5 years under the following conditions:
  - 8760 power-on hours per year
  - Active 100% of power-on hours
  - Typical operating conditions[2]: 2GB module: 16 GB/day; 4GB module: 32 GB/day; 8GB module: 64 GB/day; 16GB module: 128 GB/day
- Static and dynamic wear-leveling
- 15-bit error correction code (ECC)
- Reliability reporting

- Capacity (unformatted)[3]: 2GB, 4GB, 8GB, or 16GB
- Form factor
  - Standard (36.9mm x 26.6mm x 9.6mm)
- Voltage: 5V ±5%
- Operating temperature
  - Commercial (0°C to +70°C)
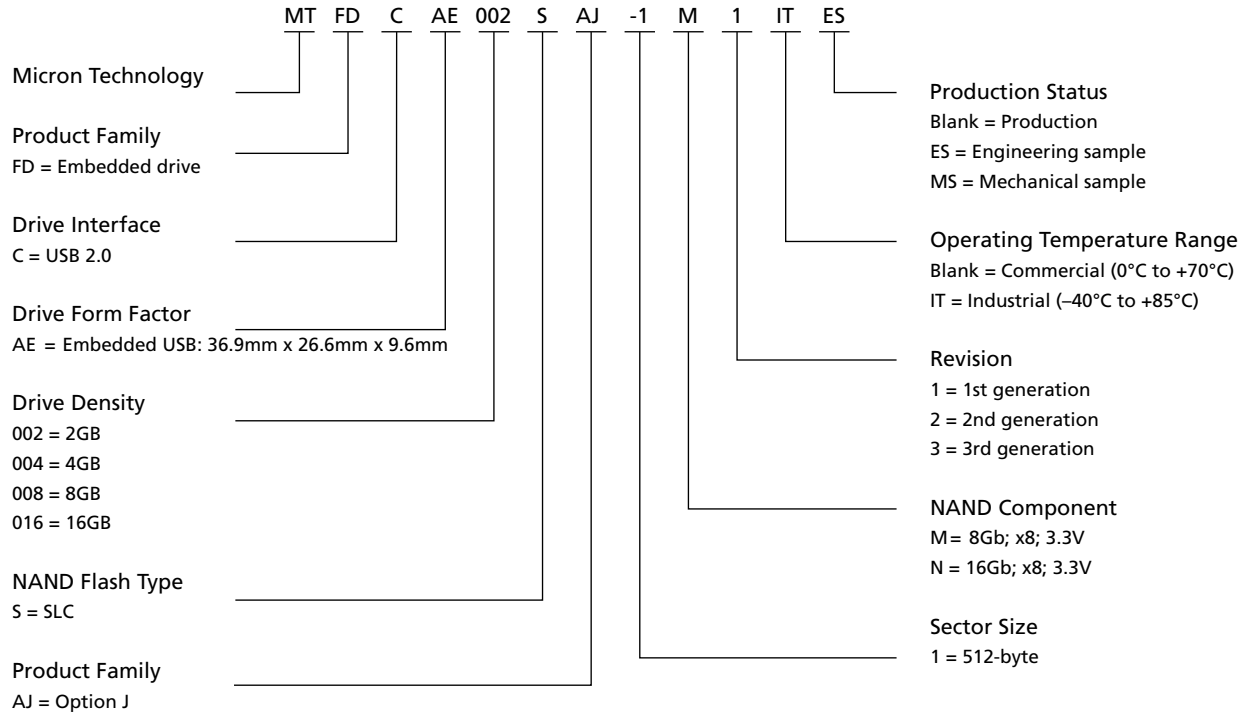 - Industrial (–40°C to +85°C)

Notes: 1. Typical transfer rate measured with H2BENCH 3.6.
        2. Assumes that 70% of total usable drive capacity contains static files.
        3. 1GB = 1 billion bytes; formatted capacity is less.

Warranty: Contact your Micron sales representative for further information regarding the product, including product warranties.

Products and specifications discussed herein are subject to change by Micron without notice.

Part Numbering Information

Micron's embedded USB drives are available in different configurations and densities. Visit www.micron.com for a list of valid part numbers.

Figure 1: Part Number Chart

MT FD C AE 002 S AJ -1 M 1 IT ES

Micron Technology

Product Family
FD = Embedded drive

Drive Interface
C = USB 2.0

Drive Form Factor
AE = Embedded USB: 36.9mm x 26.6mm x 9.6mm

Drive Density
002 = 2GB
004 = 4GB
008 = 8GB
016 = 16GB

NAND Flash Type
S = SLC

Product Family
AJ = Option J

Production Status
Blank = Production
ES = Engineering sample
MS = Mechanical sample

Operating Temperature Range
Blank = Commercial (0°C to +70°C)
IT = Industrial (–40°C to +85°C)

Revision
1 = 1st generation
2 = 2nd generation
3 = 3rd generation

NAND Component
M = 8Gb; x8; 3.3V
N = 16Gb; x8; 3.3V

Sector Size
1 = 512-byte

General Description

Micron embedded universal serial bus (USB) mass storage drives provide 2GB, 4GB, 8GB, or 16GB of USB 2.0-compatible memory storage in a small form factor. The embedded USB drive is an ideal solution for applications that require low cost and high reliability. Typical applications include PC caching and boot drives for embedded computing, server, and networking systems.

High performance, reliability, and easy implementation make Micron embedded USBs an ideal storage solution. To consistently deliver the best possible performance, the embedded USB uses only SLC NAND Flash, and all densities use two x8 NAND channels to the controller. In addition to being fast, SLC NAND Flash offers solid reliability, coupled with ECC and wear leveling. The USB system interface is widely available in many system designs and is easy to implement, enabling rapid time to market.

The embedded USB consists of two TSOP-packaged Micron NAND Flash components, a USB controller, and a 10-pin USB connector on a PCB. Different densities are available depending on the number of die in each package and the density of each NAND Flash die. The drive operates at 5V ±5%. It uses industry-standard 10-pin connectors and supports USB Specification, Revision 2.0. It is also backward compatible with Revision 1.1 and can be used with operating systems that support USB Mass Storage Class Specification, Revision 1.0.
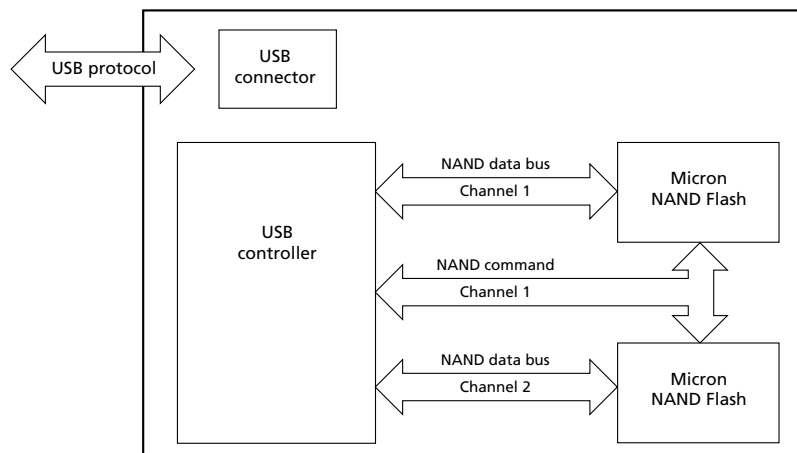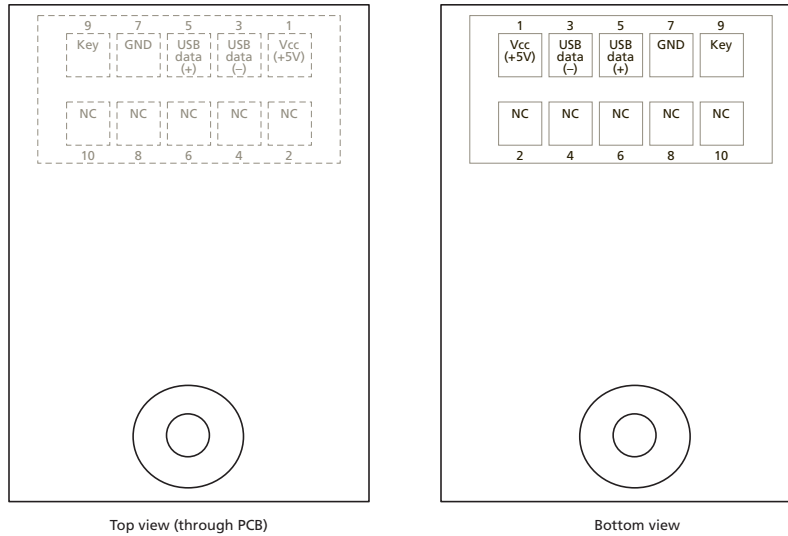
Figure 2: Functional Block Diagram

Table 1: Nominal Package Dimensions, Density, and Weight

	Value	Unit
Height	9.6	mm
Width	26.6	mm
Length	36.9	mm
Density	1, 2, 4, 8	GB
Unit weight	4.5	g

Figure 3: Pin Assignments: 2 x 5 Connector

9	7	5	3	1
Key	GND	USB data (+)	USB data (–)	Vcc (+5V)
NC	NC	NC	NC	NC
10	8	6	4	2

Top view (through PCB)

1	3	5	7	9
Vcc (+5V)	USB data (–)	USB data (+)	GND	Key
NC	NC	NC	NC	NC
2	4	6	8	10

Bottom view

Note: 1. Diagram not to scale.

Table 2: Signal/Pin Descriptions

Symbol	Type	Function
USB data (+), USB data (–)	I/O	**Data inputs/outputs**: The bidirectional I/Os transfer address, data, and instruction information. Data is output only during READ operations; at other times the I/Os are inputs.
V_{CC}	Supply	V_{CC} power supply pin.
V_{SS}	Supply	V_{SS} ground connection
NC	–	**No connect**: NC pins are not internally connected. These pins can be driven or left floating.
Key	–	This pin is keyed.

Error Management

The embedded USB incorporates advanced technology for defect and error management. It uses various combinations of hardware-based error correction algorithms and firmware-based wear-leveling algorithms.

Over the life of the drive, uncorrectable errors may occur. An uncorrectable error is defined as data that is reported as successfully programmed to the drive, but when it is read out of the drive, the data differs from what was programmed. See the Uncorrectable Bit Error Rate Table.

The mean time between failures (MTBF) can be predicted based on component reliability data obtained by following the methods referenced in the Telecordia SR-332 reliability prediction procedures for electronic equipment.

Table 3: System Reliability

Density	MTFB (Operating Hours)
2–16GB	>1 million device hours

Table 4: Uncorrectable Bit Error Rate

Uncorrectable Bit Error Rate (BER)[1]	Operation
<1 bit error in 10^{15} bits	READ

Note: 1. BER is measured with a WRITE-to-READ ratio of 1:1.

Wear-Leveling Algorithm

The controller adds a built-in RAM register unit to record the erase count of each block. Accordingly, the controller can decide the frequency of wear leveling and choose the proper blocks to swap. This technique successfully averages the erase count of the data blocks. Also, an enhanced wear leveling algorithm now includes most static blocks in the recycling pool. Increasing the number of blocks makes the wear-leveling algorithm more robust, and in turn extends product life.

Electrical Characteristics

Stresses greater than those listed may cause permanent damage to the drive. This is a stress rating only, and functional operation of the drive at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

Table 5: Absolute Maximum Ratings

Parameter/Condition	Symbol	Min	Max	Unit
V_{CC} supply voltage	V_{CC}	−0.6	5.25	V

Table 6: DC and Operating Characteristics

Parameter/Condition	Symbol	Min	Typ	Max	Unit	Condition
Standby current	Isb	–	50	60	mA	V_{CC} = 5V
Active current	$I_{CC}1$	–	100	120	mA	V_{CC} = 5V

Table 7: Recommended Operating Conditions

Parameter/Condition		Symbol	Min	Typ	Max	Unit
Operating temperature	Commercial	T_A	0	–	70	°C
	Industrial		−40	–	85	°C
V_{CC} supply voltage		V_{CC}	4.75	5.00	5.25	V
Ground supply voltage		V_{SS}	0	0	0	V

Table 8: Shock and Vibration

Parameter/Condition	Specification
Shock	1500g/0.5ms
Vibration	5–500Hz at 3.1G

Compliance

Micron embedded USB drives comply with the following requirements:

- CE (Europe): EN55022, 2006 Class B and EN55024, 1998 + A1: 2001 + A2:2003
- FCC: CFR Title 47, Part 15, ICES-003, all Class B
- UL (US): approval to UL-60950-1, 2nd Edition, 2007-03-27, IEC 60950-1:2005, 2nd Edition
- RoHS, "green" package

Configuration

The following configuration options are available:

- Micron's embedded USB drive can be configured as a boot drive.
- The standard fix configuration should be mounted as local drive.
Note: The embedded USB drive cannot be configured as a removable drive.

Mechanical Information

The 10-pin (2 x 5) female electrical connector has a height of 7.4mm, a pitch of 2.54 mm, and supports the standard USB 2.0 interface. A mounting hole is also provided on the PCB for a stable, reliable connection to the mounting board.

The motherboard pin headers listed in Table 9 are compatible with Micron's embedded USB drives. Pin headers that are not listed may also be compatible.

Table 9: Compatible Pin Headers

Manufacturer	Part Number	Type
Pinrex	212-92-05GB01	SMT
	210-92-05GB01	Straight
Amtek	PHIFS25-205GB	Press fit
	PHIS25-205GB	Straight

Reference Documents

Reference documentation for the USB 2.0 standard (USB 2.0 specification, technical documents, compliance test procedures, and other related documents) can be found at www.usb.org/developers/docs.

Package Dimensions

Figure 4: Embedded USB Package
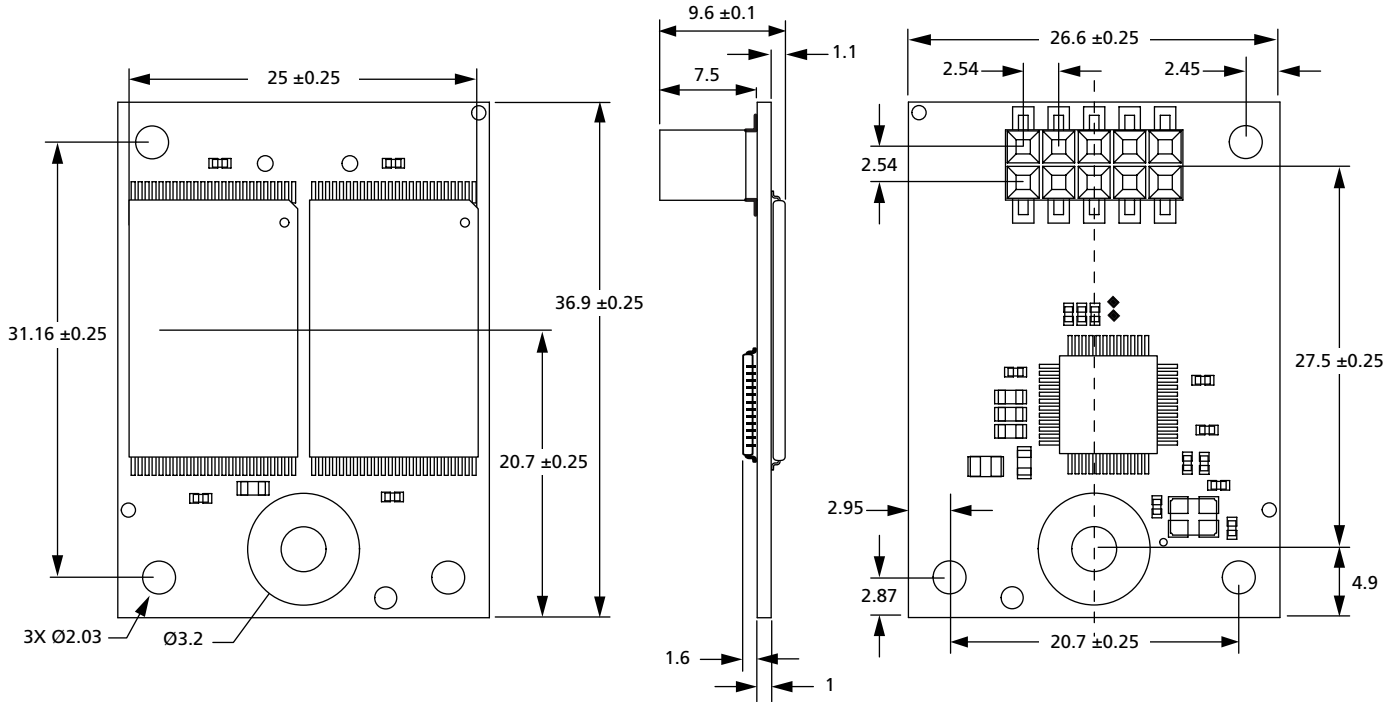
Note: 1. All dimensions are in millimeters.

Revision History

Rev. D – 4/13

- Updated packaging drawing

Rev. C – 1/13

- Updated packaging section

Rev. B, Advance – 4/11

- Removed 'password protection' from features; added 'configuration' section

Rev. A, Advance – 4/10

- Initial release